



Hostaform® acetal copolymer grade S 9364 XAP®2 ECO-B is a highly impact modified grade for demanding applications. Hostaform® S 9364 XAP®2 ECO-B provides a significant improvement in impact strength and flexibility over standard impact modified grades. Hostaform® S 9364 XAP®2 exhibits exceptional low emission performance meeting or exceeding the requirements of many automotive markets.

ECO-B: Hostaform ECO-B is a POM-Copolymer with the same properties and performance as standard grades but produced with sustainability in mind. Using a mass-balance approach, biogenic feedstocks are used to offset the use of fossil-based raw materials and decrease greenhouse gas emissions. The process is audited and certified according to the ISCC Plus mass balance approach.

Product information

Product information			
Resin Identification	POM-I		ISO 1043
Part Marking Code	>POM-I<		ISO 11469
•			
Rheological properties			
Melt volume-flow rate	4	cm ³ /10min	ISO 1133
Temperature	190	°C	
Load	2.16	kg	
Moulding shrinkage, parallel	1.6	•	ISO 294-4, 2577
Moulding shrinkage, normal	1.5	%	ISO 294-4, 2577
Typical mechanical properties			
Tensile modulus	1650	MPa	ISO 527-1/-2
Tensile stress at yield, 50mm/min	43	MPa	ISO 527-1/-2
Tensile strain at yield, 50mm/min	16		ISO 527-1/-2
Flexural modulus	1550	MPa	ISO 178
Flexural stress at 3.5%	42	MPa	ISO 178
Charpy impact strength, 23°C	N	kJ/m²	ISO 179/1eU
Charpy impact strength, -30°C	N	kJ/m²	ISO 179/1eU
Charpy notched impact strength, 23°C	21	kJ/m²	ISO 179/1eA
Charpy notched impact strength, -30°C	11	kJ/m²	ISO 179/1eA
Izod notched impact strength, 23°C	20	kJ/m ²	ISO 180/1A
Izod notched impact strength, -40°C	10.0	kJ/m²	ISO 180/1A
Hardness, Rockwell, M-scale	48		ISO 2039-2
Poisson's ratio	0.42 ^[C]		
[C]: Calculated			
Thermal properties			
Melting temperature, 10°C/min	165	°C	ISO 11357-1/-3
Temperature of deflection under load, 1.8 MPa		°C	ISO 75-1/-2
Temperature of deflection under load, 0.45 MPa	140		ISO 75-1/-2
Coefficient of linear thermal expansion		E-6/K	ISO 11359-1/-2
(CLTE), parallel			
Coefficient of linear thermal expansion (CLTE),	110	E-6/K	ISO 11359-1/-2
normal			

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Physical/Other properties

Humidity absorption, 2mm	0.25 %	Sim. to ISO 62
Water absorption, 2mm	0.8 %	Sim. to ISO 62
Density	1360 kg/m ³	ISO 1183

Injection

Drying Recommended	no	
Drying Temperature	100	°C
Drying Time, Dehumidified Dryer	3 - 4	h
Processing Moisture Content	≤0.2	%
Melt Temperature Optimum	190	°C
Min. melt temperature	180	°C
Max. melt temperature	200	°C
Screw tangential speed	≤0.3	m/s
Mold Temperature Optimum	65	°C
Min. mould temperature	60	°C
Max. mould temperature	70	°C
Hold pressure range	60 - 120	MPa
Back pressure	2	MPa

Characteristics

Processing Injection Moulding, Extrusion

Delivery form Pellets

Additives Release agent

Special characteristics High impact or impact modified

Sustainability Bio-Content

Additional information

Processing Notes Pre-Drying

Drying is suggested to help achieve low emission performance and to counter if material has contacted moisture through improper storage and handling.

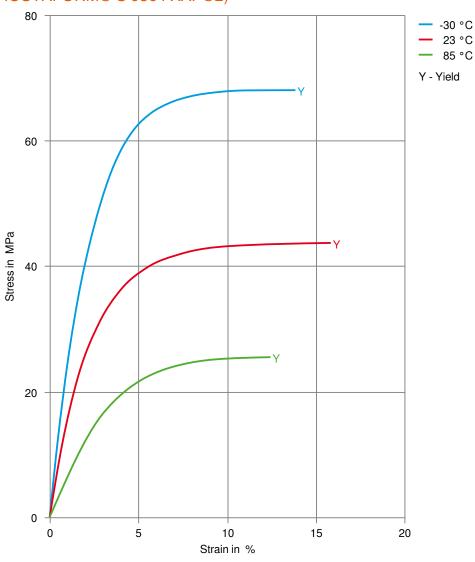
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Stress-strain (measured on HOSTAFORM® S 9364 XAP®2)

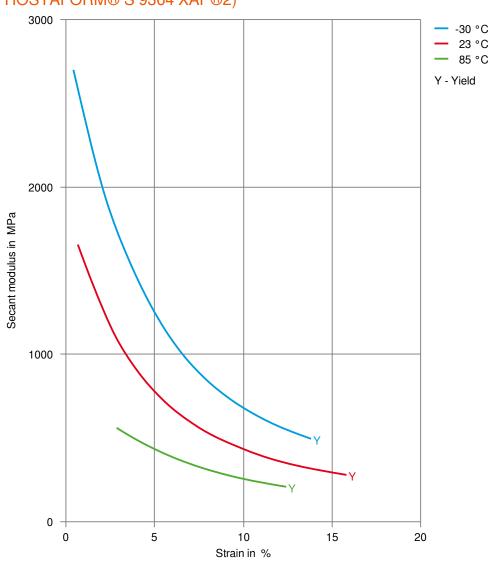


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Secant modulus-strain (measured on HOSTAFORM® S 9364 XAP®2)

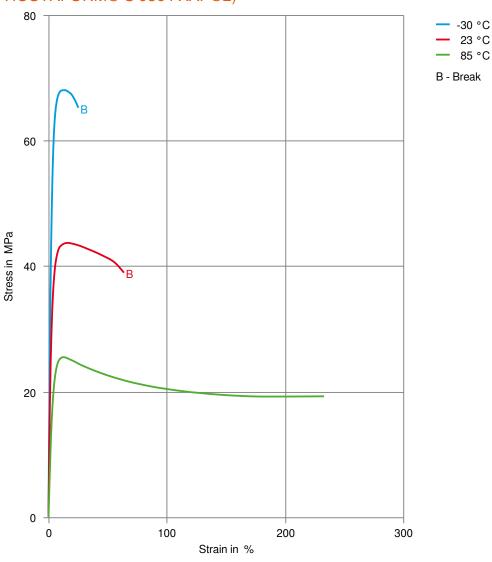


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Stress-strain, 50mm/min (measured on HOSTAFORM® S 9364 XAP®2)



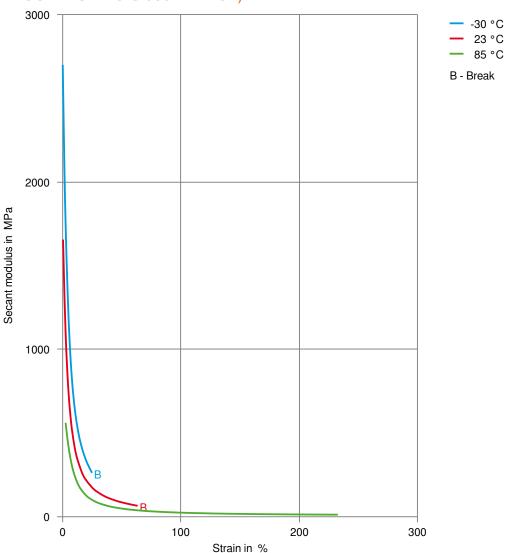
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HOSTAFORM® S 9364 XAP®2 ECO-B

Secant modulus-strain, 50mm/min (measured on HOSTAFORM® S 9364 XAP®2)



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